

Title (en)

Method and system for mounting electric components

Title (de)

Verfahren und Vorrichtung zur Montage von elektrischen Bauteilen

Title (fr)

Méthode et dispositif de montage de composants électriques

Publication

**EP 0959654 A2 19991124 (EN)**

Application

**EP 99303907 A 19990519**

Priority

JP 13696298 A 19980519

Abstract (en)

A method of mounting a plurality of electric components on a circuit substrate and thereby producing an electric circuit, including the steps of taking, immediately before each of the electric components is mounted on the circuit substrate, a first image of a first portion of the circuit substrate on which the each electric component is to be mounted and a second portion of the circuit substrate that is adjacent to the first portion, mounting the each electric component on the circuit substrate, taking, immediately after the each electric component is mounted on the circuit substrate, a second image of the mounted electric component and the second portion adjacent to the mounted electric component, and inspecting, by comparing the first and second images with each other, a state in which the each electric component is mounted on the circuit substrate. <IMAGE>

IPC 1-7

**H05K 13/04**

IPC 8 full level

**H05K 13/04** (2006.01); **H05K 13/08** (2006.01)

CPC (source: EP US)

**H05K 13/0812** (2018.07 - EP US); **Y10T 29/4913** (2015.01 - EP US); **Y10T 29/49131** (2015.01 - EP US); **Y10T 29/49133** (2015.01 - EP US); **Y10T 29/49769** (2015.01 - EP US); **Y10T 29/53087** (2015.01 - EP US); **Y10T 29/53174** (2015.01 - EP US); **Y10T 29/53178** (2015.01 - EP US)

Citation (applicant)

- JP S62298750 A 19871225 - OMRON TATEISI ELECTRONICS CO
- JP H07183697 A 19950721 - MATSUSHITA ELECTRIC IND CO LTD

Cited by

CN108521718A; DE102005044866A1; US7239399B2; US10926298B2; US6765666B1; US10556240B2; WO2023198603A1; WO0212870A3; US7773220B2; US11167384B2; US7346419B2; US7346420B2

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DOCDB simple family (application)

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